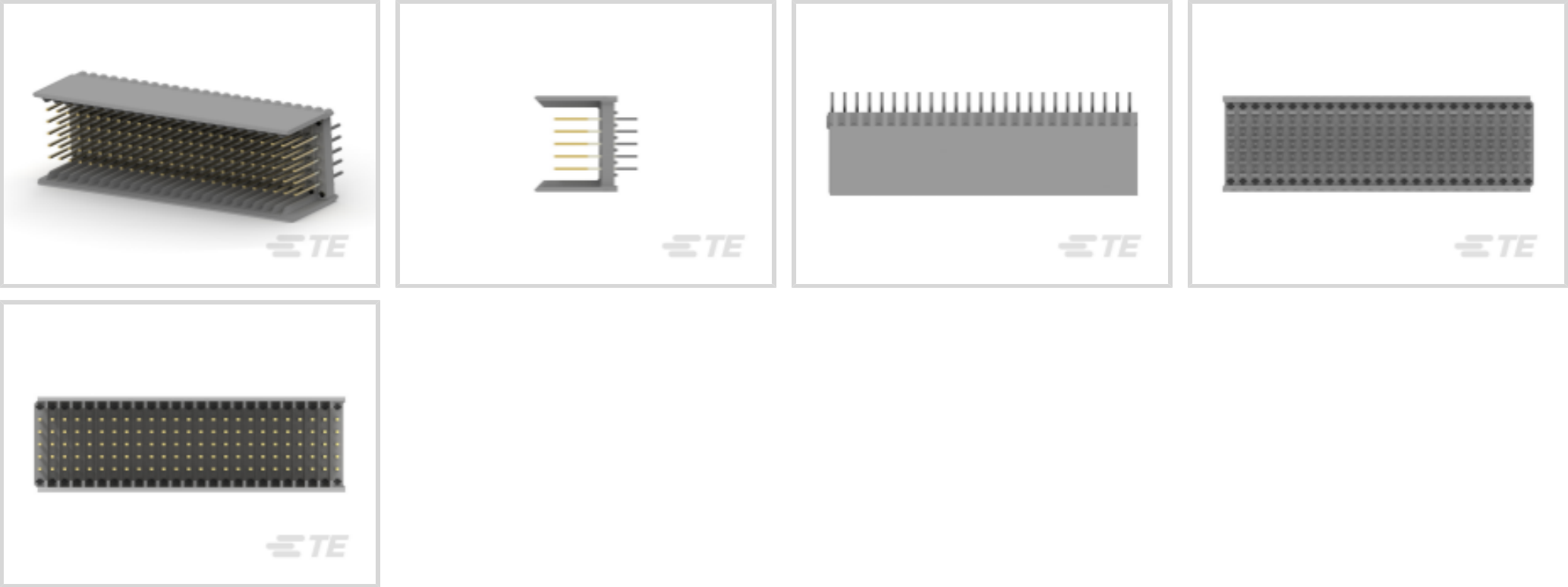




Connectors > PCB Connectors > Backplane Connectors > Hard Metric Backplane Connectors >

Hard Metric Male Connector: Traditional Backplane, Mezzanine, 2mm



PCB Connector Assembly Type: **PCB Mount Header**

Data Rate: **≤1 Gb/s**

Number of Columns: **25**

Number of Rows: **5**

Backplane Architecture: **Mezzanine**

[All Hard Metric Male Connector: Traditional Backplane, Mezzanine, 2mm \(124\)](#)

Features

Product Type Features

|                                   |                       |
|-----------------------------------|-----------------------|
| Backplane Interface Type          | 2mm HM                |
| Connector System                  | Board-to-Board        |
| Connector & Contact Terminates To | Printed Circuit Board |
| PCB Connector Assembly Type       | PCB Mount Header      |
| Sealable                          | No                    |

Configuration Features

|                        |           |
|------------------------|-----------|
| Number of Columns      | 25        |
| Number of Rows         | 5         |
| Backplane Architecture | Mezzanine |
| Number of Positions    | 125       |
| PCB Mount Orientation  | Vertical  |

Signal Characteristics



|           |         |
|-----------|---------|
| Data Rate | ≤1 Gb/s |
|-----------|---------|

Body Features

|                       |      |
|-----------------------|------|
| Primary Product Color | Gray |
|-----------------------|------|

Contact Features

|                                                |                 |
|------------------------------------------------|-----------------|
| Feedthrough Post Length                        | 3.7 mm          |
| CompactPCI Designation                         | None            |
| Contact Type                                   | Pin             |
| Contact Underplating Material                  | Nickel          |
| PCB Contact Termination Area Plating Material  | Tin             |
| Contact Base Material                          | Phosphor Bronze |
| Contact Mating Area Plating Material           | Gold            |
| Contact Mating Area Plating Material Thickness | .76 µm[30 µin]  |
| Contact Current Rating (Max)                   | 1.5 A           |

Termination Features

|                                             |                          |
|---------------------------------------------|--------------------------|
| Termination Method to Printed Circuit Board | Through Hole - Press-Fit |
|---------------------------------------------|--------------------------|

Mechanical Attachment

|                         |             |
|-------------------------|-------------|
| Connector Mounting Type | Board Mount |
|-------------------------|-------------|

Housing Features

|                    |                |
|--------------------|----------------|
| Housing Material   | Polyester - GF |
| Centerline (Pitch) | 2 mm[.078 in]  |

Dimensions

|                         |          |
|-------------------------|----------|
| Backplane Module Length | 49.88 mm |
|-------------------------|----------|

Usage Conditions

|                             |                            |
|-----------------------------|----------------------------|
| Operating Temperature Range | -55 - 125 °C[-67 - 257 °F] |
|-----------------------------|----------------------------|

Operation/Application

|                     |        |
|---------------------|--------|
| Shielded            | No     |
| Circuit Application | Signal |

Industry Standards

|                        |          |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Packaging Features

|                    |    |
|--------------------|----|
| Packaging Quantity | 10 |
|--------------------|----|



Packaging Method

Tube

Product Compliance

For compliance documentation, visit the product page on TE.com>

|                                               |                                                                                                                               |
|-----------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------|
| EU RoHS Directive 2011/65/EU                  | Compliant                                                                                                                     |
| EU ELV Directive 2000/53/EC                   | Compliant                                                                                                                     |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                                                                                       |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JAN 2024 (240)<br>Candidate List Declared Against: JAN 2024 (240)<br>Does not contain REACH SVHC |
| Halogen Content                               | Not Low Halogen - contains Br or Cl > 900 ppm.                                                                                |
| Solder Process Capability                     | Not applicable for solder process capability                                                                                  |

Product Compliance Disclaimer

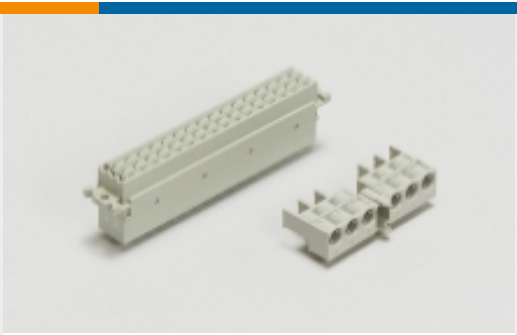
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

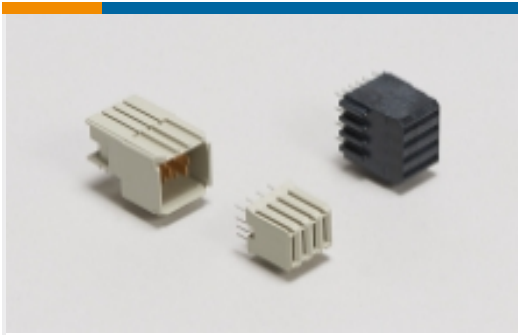
TE Part # 5100145-1  
Z-PACK/B25 RAF 125P

TE Part # 90755-1  
SEATING TOOL ASSY H.M. 175 PIN

Also in the Series | Z-PACK 2mm HM



Backplane Connector Housings(4)



Backplane Power Connectors(6)



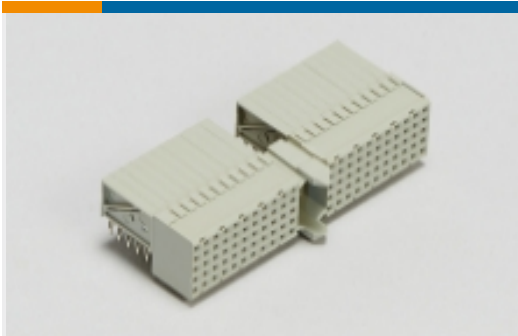
Connector Caps & Covers(62)



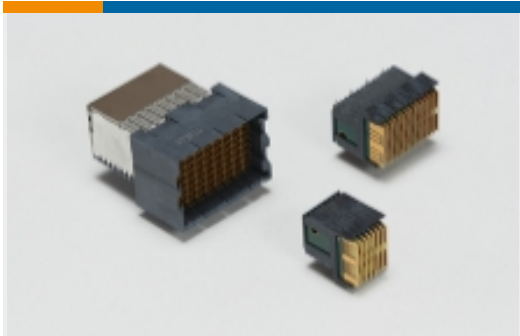
Connector Contacts(2)



Connector Hardware(97)



Hard Metric Backplane Connectors (267)



High Speed Backplane Connectors(1)



Insertion & Extraction Tools(2)



Rectangular Power Connectors(87)

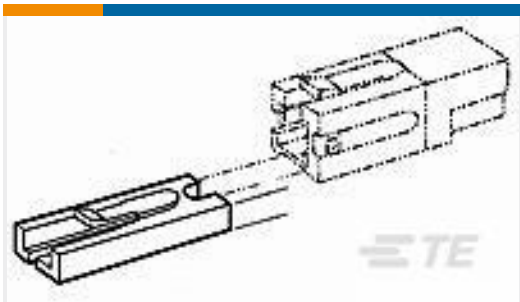
Customers Also Bought



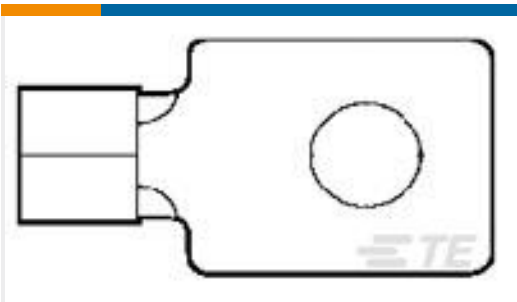
TE Part # 292303-1  
Std USB Type A, R/A, T/H



TE Part # 292304-1  
STD USB TYPE B, R/A, T/H



TE Part # 53885-1  
SURF MT ADAPTER,POWER LK,SRS2



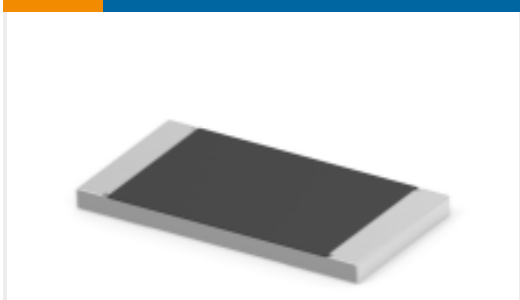
TE Part # 34489  
TERMINAL,SOLIS SPD 14-12 10



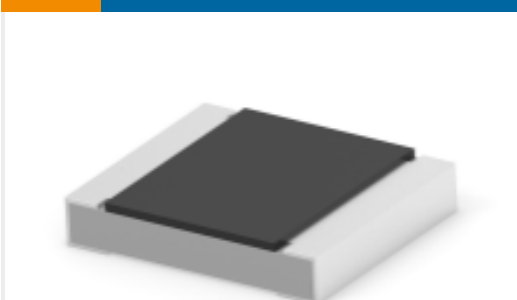
TE Part # 6469083-1  
HMZD 3PAIR, HDR ASSY, 25MM MOD



TE Part # 1-2176567-4  
3430 A3 1% 43K 100ppm 1k RL



TE Part # 2-2176530-6  
3504G 3A 1K0 1% 1K RL



TE Part # 1-2176588-7  
RLC73K 2E R887 1% 1K RL

Documents



Product Drawings

2MM HDR, 125 POS 9.7MM

English

CAD Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_5100785-1\_B.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_5100785-1\_B.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_5100785-1\_B.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Application Specification

English